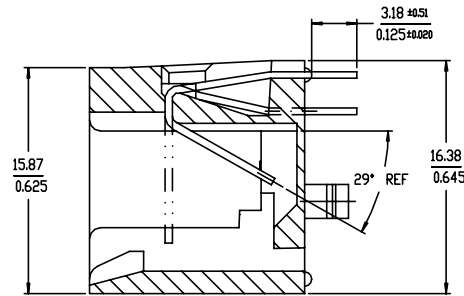
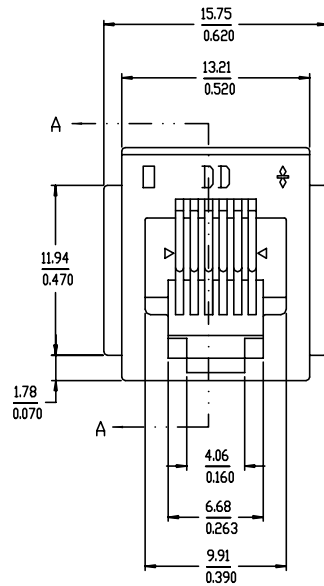
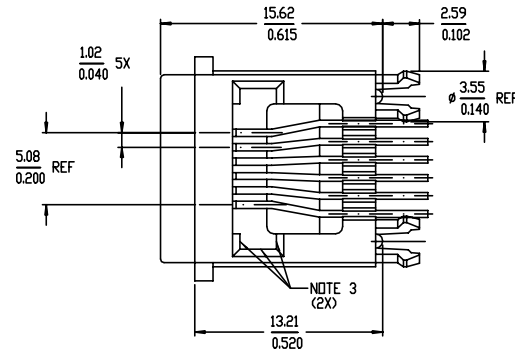
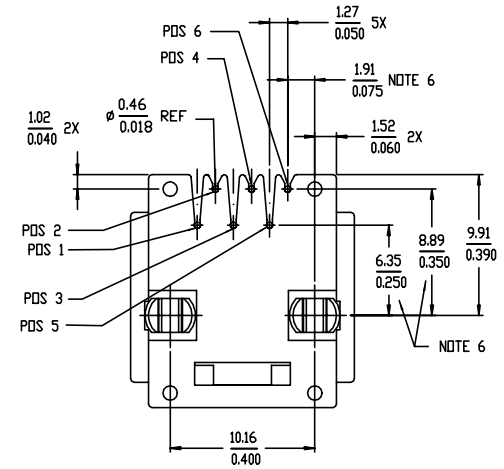


PRODUCT NO.
SEE CHART



SECTION A-A



mat'l. code		surface		tolerance		projection		product family	
		ISO1302 ✓		ISO1101 ISO406				MOD JACK	
l trechn nodr		date		tolerances unless other		wise specified		title	
N N04-0102		YS 11/23/04		angle		mm		6 POS VERT. SNAP PEG	
P N08-0097		SH 09/25/08		0°±2'		scale		PCB III MOD JACK ASSY	
R N08-0170		SH 10/10/08		0°±2'		2.0			
S ELX-N-010713		SH MM 3/14/12		dr		M CHENG 7/13/01		dwg no	
				enr		M CHENG 7/13/01		sheet 1 of 2	
				chr		M CHENG 7/18/01		size	
				appd		J HSIA 7/20/01		A4	
sheet		revisions		s		FCI		type Product Customer Drawing	
index		sheet		1 2					

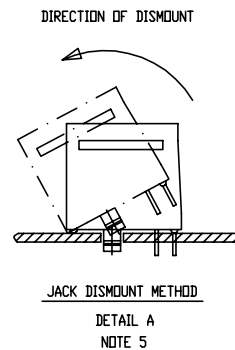
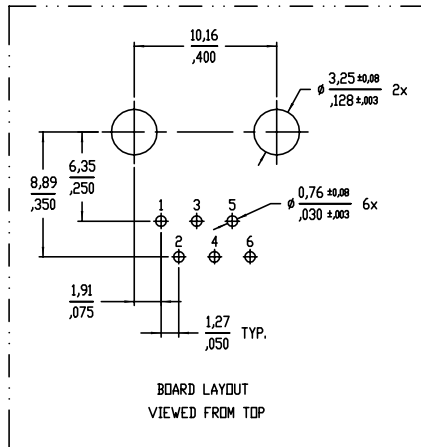
PRODUCT NO.	POSITIONS LOADED	CONTACT PLATING	NOTES
90512-001 -001LF -011LF	ALL	5u' Au + high performance lubricant	BLACK
-002 -002LF -012LF	ALL	5u' Au + high performance lubricant	BLACK ⑩
-003 -003LF -013LF	2,3,4,5	5u' Au + high performance lubricant	BLACK
-004 -004LF -014LF	2,3,4,5	50u' / 1.27u GXT	BLACK
-005 -005LF -015LF	3,4	5u' Au + high performance lubricant	BLACK
-006 -006LF	ALL	5u' Au + high performance lubricant	GREY
-007 -007LF	ALL	5u' Au + high performance lubricant	GREY ⑩
-008 -008LF	3,4	5u' Au + high performance lubricant	GREY

PRODUCT NO.	POSITIONS LOADED	CONTACT PLATING	REMARKS
90512-101 -101LF -111LF	ALL	5u' Au + high performance lubricant	NOT TOOLED
-102 -102LF -112LF	ALL	5u' Au + high performance lubricant	NOT TOOLED
-103 -103LF -113LF	2,3,4,5	5u' Au + high performance lubricant	NOT TOOLED
-104 -104LF -114LF	2,3,4,5	50u' / 1.27u GXT	NOT TOOLED
-105 -105LF -115LF	3,4	5u' Au + high performance lubricant	NOT TOOLED

LEAD FREE PRODUCT NO.
0: MEETS WAVE SOLDER PROCESS PRODUCT NO.
1: MEETS PIP PROCESS PRODUCT NO.

NOTES :

- P/NO WITH DASH 0XX -NORMAL WAVE SOLDERING APPLICATION.
P/NO WITH DASH 1XX -IR REFLOW APPLICATION (NOT TOOLED).
- PACKAGING SPEC. BUS-14-164.
- SCRATCH MARKS ACCEPTABLE ON THESE SURFACES.
- JACK IS FOR 1,57/.062 THICK PCB.
- SHOULD THE JACK NEED TO BE DISMOUNTED FROM THE PCB, PLS REMOVE JACK AS PER RECOMMENDED METHOD HEREIN. (DETAIL A) NIPPING THE LEGS OF THE PEG TOGETHER IS DISALLOWED, OTHERWISE LEG BREAKAGE MAY OCCUR.
- THESE DIMENSIONS ARE TAKEN FROM THE TOP OF THE PEG.
- THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.
- THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.60mm MINIMUM THICK CIRCUIT BOARD.
- IF LF P/N PACKAGING MEETS GS-14-920 SPECIFICATION.
- EQUIVALENT THICKNESS Au AND GXT PLATING HAVE SAME FUNCTION AND THEY ARE ALTERNATIVE BY THE CUSTOMER.



mat'l. code		surface ISO1302 ✓		tolerance ISO1101 ISO406		projection mm		product family MOD JACK	
l	tr	ec	n	no	dr	date	tolerances unless otherwise specified		
N	N04-0102	YS				11/23/04	angle	0.X±0.3	6 POS VERT. SNAP PEG PCB III MOD JACK ASSY
P	N08-0097	SH				09/25/08	line	0.XX±0.15	
R	N08-0170	SH				10/10/08	0'±2'	0.XXX±0.05	
S	ELX-N-010713	SH	MNO			3/14/12	dr	M CHENG	7/13/01
							enr	M CHENG	7/13/01
							chr	M CHENG	7/18/01
							appd	J HSIA	7/20/01
sheet	revision								
index	sheet								